(Application Number)

## DECLARATION FOR PATENT APPLICATION

TO

As a below named inventor, I hereby declare that: My residence, post office address and citizenship are as stated below next to my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **HANDLING DEVICE FOR CHIP ELECTRONIC COMPONENTS AND** HANDLING METHOD FOR CHIP ELECTRONIC COMPONENTS the specification of which is attached hereto unless the following box is checked: as United States Application Number or PCT International was filed on \_ and was amended on \_\_\_\_\_ (if applicable). Application Number I hereby state that I have reviewed and understand the contents of the above identified specification. including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56. I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed. Priority. Priority Date Prior Foreign Application(s) Claimed March 28, 2003 Yes No 2003-091539 Japan (Day/Month/Year (Country) (PCT) (Number)  $\boxtimes$ Filed) November 27, 2003 Yes No 2003-397695 Japan (Day/Month/Year (Country) (PCT) (Number)  $\boxtimes$ П Filed) I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below. (Filing Date) (Application Number)

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information

(Filing Date)

Address

Japan

TO

which is material to of the prior applicati	patentability as on and the nati	defined in 37 CFR § 1.5 onal or PCT International	6 which became ava I filing date of this ap	ilable between plication.	the filing date
(Application Number)		(Filing Date) (Status - abandor		- patented, pending, ned)	
(Application Number)		(Filing Date)	(Status – patented, pending, abandoned)		
I hereby appoint the business in the Pate Joseph R. Keating, Christopher A. Benr	ent and Tradem Reg. No. 37,36		prosecute this applic rewith:	cation and to tr	ansact all
Address all correspondence to:		Keating & Bennett LLP 10400 Eaton Place, Suite 312 Fairfax, VA 22030 (703) 385-5200			
on information and I knowledge that willfunder Section 1001	pelief are believ ul false stateme of Title 18 of th	made herein of my own red to be true; and further ents and the like so made the United States Code an ation or any patent issued	r that these statemer : are punishable by fi id that such willful fal	nts were made ne or imprison	with the ment, or both.
Full name of first inventor (given name, family name)  Yutaka TAKAGI				<u> </u>	
Inventor's signature	Yutak	n Takasi	Date	3/25/2	2004
Residence Hikawa-gun, Shimane-ken, Japan				Citizenship	Japan
Post Office Address	c/o Murata M Japan	anufacturing Co., Ltd., 26	i-10, Tenjin 2-chome	, Nagaokakyo-	shi, Kyoto-fu
Full name of second	inventor (give	n name, family name)	EIJI KARINO		
Inventor's signature	- Esia	Karino	Date	3/19	12004
Residence Oha	ra-gun, Shima	ine-ken, Japan		Citizenship	Japan
Post Office					